# 506806997 08/08/2021 PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
LUOHAI ZHENG		03/05/2021
JIGUANG LU		03/05/2021
WANGSHENG ZHOU		03/05/2021
JIANJUN ZHANG		03/04/2021
JUNJIE SHI		03/05/2021
HUJIA CHEN		03/05/2021
JUN ZANG		03/05/2021
CHUANBING DAI		03/04/2021
QING QIN		03/04/2021
YIGE CAI		03/08/2021

# **RECEIVING PARTY DATA**

Name:	TENCENT TECHNOLOGY (SHENZHEN) COMPANY LIMITED
Street Address:	35/F, TENCENT BUILDING, KEJIZHONGYI ROAD
Internal Address:	MIDWEST DISTRICT OF HI-TECH PARK, NANSHAN DISTRICT
City:	SHENZHEN, GUANGDONG
State/Country:	CHINA
Postal Code:	518057

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17200594

## CORRESPONDENCE DATA

Fax Number:	(650)843-4001				
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.					
Phone:	6508434000				
Email:	cheryl.rogers@morganlewis.com				
Correspondent Name:	YALEI SUN				
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Address Line 2:	1400 PAGE MILL ROAD				
Address Line 4:	PALO ALTO, CALIFORNIA 94304				

ATTORNEY DOCKET NUMBER:	031384-7089-US	
NAME OF SUBMITTER:	YALEI SUN	
SIGNATURE:	/Yalei Sun/	
DATE SIGNED:	08/08/2021	
Total Attachments: 11		
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## **COMBINED ASSIGNMENT & DECLARATION**

### **ASSIGNMENT**

WHEREAS, I hereinafter called the "Assignor", has made the invention described in the United States patent application entitled <u>METHODS, SYSTEMS, AND DEVICES FOR ELECTRONIC NOTE</u> <u>IDENTIFIER ALLOCATION AND ELECTRONIC NOTE GENERATION</u>, executed by Assignor on the same date as, or on a date prior to, this Assignment;

WHEREAS, <u>Tencent Technology (Shenzhen) Company Limited</u>, a corporation organized and existing under the laws of P. R. China, having a place of business at <u>35/F, Tencent Building</u>, <u>Kejizhongyi Road</u>, <u>Midwest District of Hi-tech Park</u>, <u>Nanshan District</u>, <u>Shenzhen</u>, <u>Guangdong</u>, <u>518057</u>, <u>P. R. China</u>, hereinafter called the "Assignee", desires to acquire the entire right, title and interest in and to the invention and the patent application identified above, and all patents which may be obtained for said invention, as set forth below;

NOW, THEREFORE, be it known that, for good and valuable consideration the receipt of which by the Assignor from Assignee is hereby acknowledged, the Assignor has sold, assigned and transferred, and by these presents does sell, assign and transfer to the Assignee, the entire right, title and interest for the United States in and to the invention and the patent application identified above, and any patents that may issue for said invention in the United States; together with the entire right, title and interest in and to said invention and all patent applications and patents issuing therefrom in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; together with the entire right, title and interest in and to all continuations, divisions, renewals and extensions of any of the patent applications and patents defined above; together with the right to recover all damages, including, but not limited to, a reasonable royalty, by reason of past, present, or future infringement or any other violation of patent or patent application rights; to have and to hold for the sole and exclusive use and benefit of the Assignee, its successors and assigns, to the full end of the term or terms for all such patents.

The Assignor hereby covenants and agrees, for both the Assignor and the Assignor's legal representatives, that the Assignor will assist the Assignee in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignee may elect to make covering the invention identified above; in vesting in the Assignee like exclusive title in and to all such other patent applications and patents; and that the Assignor will execute and deliver to the Assignee any and all additional papers which may be requested by the Assignee to carry out the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignor has executed this agreement.

#### DECLARATION

As the below-named inventor, I hereby declare that:

This Declaration is directed to the attached application. I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me.

I acknowledge my duty to disclose to the United States Patent and Trademark Office all information that I know to be material to the patentability of this application as defined in 37 C.F.R. § 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Further, I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application and any patent issued thereon.

Date	2021.03.05	Luohai ZHENG	L.S.
		Luohai ZHENG	
Date			L.S.
		Jiguang LU	
Date			LS
		Wangsheng ZHOU	
Date			7.6
Date		Jianjun ZHANG	

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IN TESTIMONY WHEREOF, the Assignor has executed this agreement.

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As the below-named inventor, I hereby declare that:

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Date	5 	Luohai ZHENG
Date	2021.2.5	) iguang Lu Jiguang I.U
Date		Wangsheng ZHOU
Date		Jianjun ZHANG

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IN TESTIMONY WHEREOF, the Assignor has executed this agreement.

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Date		Luohai ZHENG	Ľ.S.
Date		Jiguang LU	
Date	2021.03.05	Wavig sherg 240U Wangsheng ZHOU	L.S.
Date		Jianjun ZHANG	L.S.

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IN TESTIMONY WHEREOF, the Assignor has executed this agreement.

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Date		Luohai ZHENG	1S.
Date		Jignang LU	J.S.
Date		Wangsheng ZHOU	LS.
Date	202 <u>]. 3. 4</u>	Jianjun 24ANG Jianjun ZHANG	"L.S.

#### . 2.

Date	2021.03.05	<u>Junjie III</u> Junjie SHI	L.S.
Date		Hujia CHEN	L.S.
Date		Jun ZANG	L.S.
Date		Chuanbing DAI	L.S.
Date		Qing QIN	L8.
Date		I Yige CAI	5.8.

Date	Junjie SHI	Ł.
Date 2021.3.5	Hujia CHEN	L
	Hujia CHEN	
Date	Jun ZANG	L
Date	Chuanbing DAI	L
Date	Qing QIN	Ĺ
Date	Vige CAI	L



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Date _		Junjie SHI	L.S.
Date _		Hujia CHEN	L.S
Date _		Jun ZANG	1S
Date	7021.03.04	Chuanbing Dat	£.S
Date		Qing QIN	IS
Date		Yige CAI	L.S

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Date		Junjie SHI	L.S.
Date	<u>,</u>	Hujia CHEN	L.S.
Date		Jun ZANG	Ú.S.
Date	······································	Chuanbing DAI	LS.
Date	2021.3.4	Qing Qin : Qing Qin	<u>L.S</u> .
Date		Vige CAI	L.S.

Date		Junjie SHI	L.S.
Date		Hujia CHEN	L.S.
Date		Jun ZANG	<u> </u>
Date		Chuanbing DAI	<b>L.S</b>
Date	<sup>2</sup>	Qing QIN	LS
Date	/	Vige CAI	1.8.

RECORDED: 08/08/2021

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